

Product Change Notification - CYER-29KVQD300

 Date:
 20 Dec 2011

 Product Category:
 Memory

Device Family:

Notification subject: CCB 1055 Final Notice: Qualification of 48B TFBGA package at LPI assembly site.

Notification text:

PCN Status: Final notification

Microchip Parts Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

PCN_CYER-29KVQD300_Affected_CPN.xls PCN_CYER-29KVQD300_Affected_CPN.pdf

Description of Change:

Qualification of 48B TFBGA package at LPI assembly site.

Impacts to Data Sheet:

None

Reason for Change:

To Improve On-Time Delivery Performance

Change Implementation Status:

In Progress

Estimated First Ship Date:

January 30, 2012 (date code: 1203)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts, due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

May 12, 2011: Issued initial notification.

December 20, 2011: Issued final notification. Revised estimated first ship date from 9/15/2011 to 1/30/2012.

Note:

Qualification data will be made available upon request.

Attachment(s): PCN_CYER-29KVQD300_Affected_CPN.pdf

PCN_CYER-29KVQD300_Affected_CPN.xls

Please contact your local $\underline{\text{Microchip sales office}}$ with questions or concerns regarding this notification.

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Parts Affected
SST38VF6401
SST38VF6402
SST38VF6403
SST38VF6404
SST39LF010
SST39LF020
SST39LF040
SST39LF200A
SST39LF400A
SST39LF800A
SST39VF010
SST39VF020
SST39VF040
SST39VF1601
SST39VF1601C
SST39VF1602
SST39VF1602C
SST39VF1681
SST39VF1682
SST39VF200A
SST39VF3201
SST39VF3201B
SST39VF3202
SST39VF3202B
SST39VF400A
SST39VF6401B
SST39VF6402B
SST39VF800A
SST39WF1601
SST39WF1602
SST39WF400A
SST39WF400B
SST39WF800A
SST39WF800B